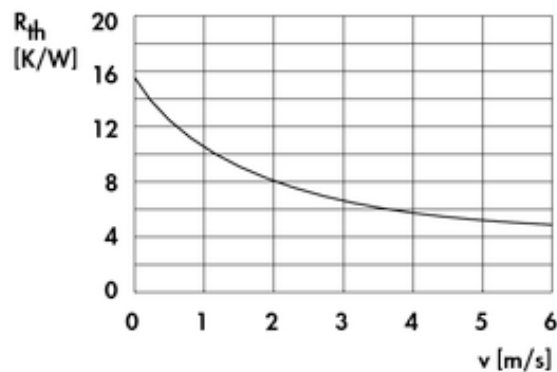
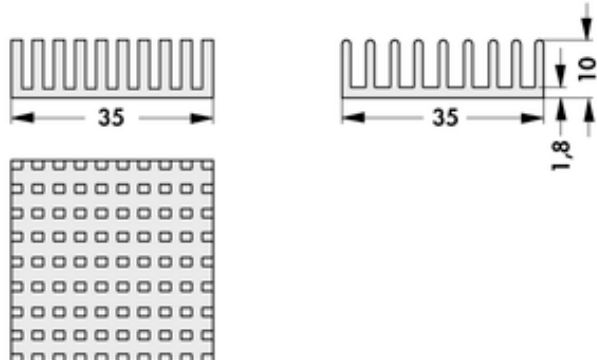
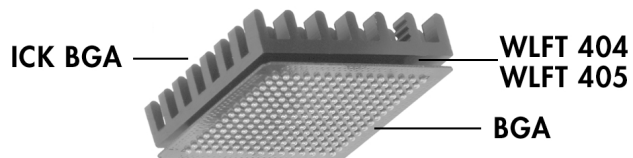


Heatsinks for BGAs / **ICK BGA 35 x 35 x 10**



35 x 35 x 10 mm, for IC design BGA and others

Parameters of article **ICK BGA 35 x 35 x 10**

R_{th} [K/W]	i 15.7
dissipation loss [W]	i 3.8
mounting method	therm. conductive foil / therm. cond. adhesive
socket	universal
suitable for processor type	universal
width [mm]	35
height [mm]	10
plate thickness [mm]	1.8
length on stock [mm]	35
surface treatment	black anodised

Accessories/ related articles

Thermally conductive foil both sides adhesive / **WLFT 404 35 x 35**

Thermally conductive foil both sides adhesive / **WLFT 405 35 x 35**